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M101C Wireless Android Module Datasheet

Version 1.2

Release Date 2018-11-15



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The document only for following list module:

M101C

Revision History

DocumentVersion	Date	Chapter	Descriptions
01	2017-07-05		Creation
1.0	2017-12-18		Add packaging
1.1	2018-05-02		Review pin description
1.2	2018-10-15		Add pin description

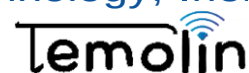


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1 Product Application Overview

M101C is a Android inside All wireless mode module. Now it Integrate with LTE/HSPA+/HSDPA/HSUPA/WCDMA/GSM, Bluetooth, WIFI, GPS on board.

This document defines the M101C module and describes its air interface and hardware interface within your application.

This document can help you to quickly understand module interface specifications, electrical and mechanical details as well as other related information of M101C module. Associated with application notes and user guide, you can use M101C module to design and set up devices applications easily.

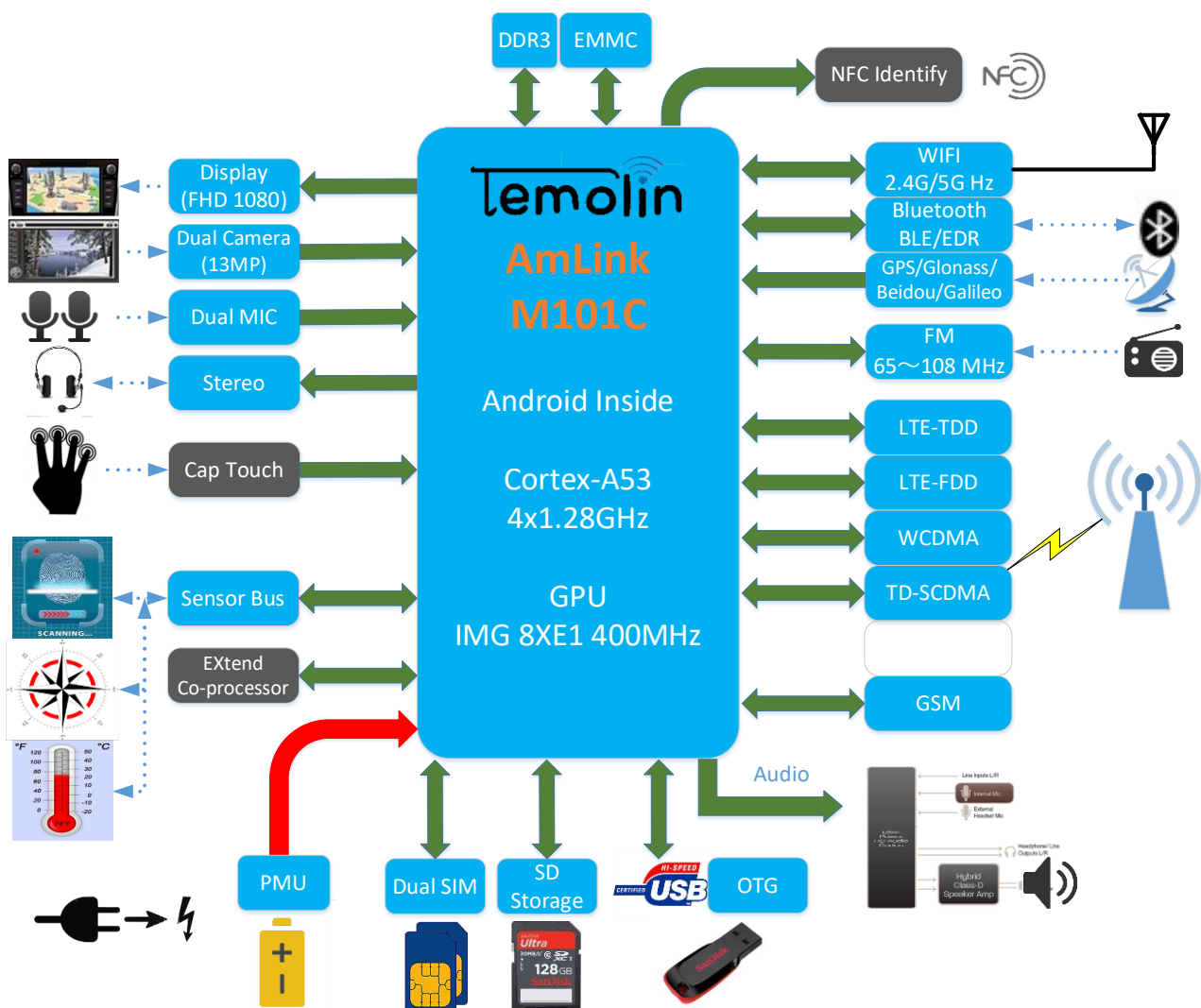


Figure: Framework of M101C Application



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2 Brief description

M101C Android world mode communication module

General Info	Description
Features	
Dimension	41x41x3.2mm
Weight	19g
Total Pins	142
Processors	Quad-core ARM® 1.28Ghz Cortex-A53 32KB L1 I-cache and 32KB L1 D-cache 512KB unified L2 cache
DRAM Memory Inside	1/2GB LPDDR-3 Up to 667Mhz
Flash Memory Inside	8/16GB eMMC
Graphics	IMG8XE1 @ 450 MHz OpenGL ES 1.1/2.0/3.0 OpenCL 1.0/1.1/1.2 DirectX9
Mobile	Dual SIM Dual Standby(DSDS)
Power supply	3.3 V to 4.2V (typical: 3.8V)
Temperature range	-40°C to 85°C
Humidity	5%~ 95%
Drop Height	1.5 meters, 6 free fall
RF Support	
RF Band	LTE FDD - B2 /B4 /B5 /B7 LTE TDD - B41 WCDMA - B2/B5 GSM - 850/1900



Air Symbol Rate	LTE FDD -Cat4 DL 150Mbps/UL 50Mbps LTE TDD -Cat4 DL 150Mbps/UL 50Mbps WCDMA -HSDPA,HSUPA,HSPA+,DC-HSPA+ -DL 42.2Mbps/UL 11.5Mbps GSM -GPRS DL 85.6kbps/UL 85.6kbps -EDGE Classs12 DL 236.8kbps/UL 236.8kbps
Multimedia	Description
Resolution	Portrait panel resolution up to FHD (1,920*1,080)
Displays	MIPI DSI interface (4 data lanes) Extended support (HDMI/LVDS) by used external chip
Primary Camera	MIPI CSI interface (4 data lanes) 13MP@30fps
Secondary Camera	MIPI CSI interface (4 data lanes) 13MP@30fps
Video	Decoder: H.264 BP/MP/HP-1080p@30fps/40Mbps MPEG-4 SP/ASP -1080p@30fps/40Mbps H.263 -1080p@30fps/40Mbps DivX 4x/5x/6x -1080p@30fps/40Mbps DivX HD/XVID -1080p@30fps/40Mbps Encoder: H.264 High profile 1080p @30fps
Audio	Audio content sampling rates supported:8kHz to 192kHz Audio content sample formats supported: 8-bit/16-bit/24-bit, Support Mono/Stereo output External CODEC I2S interface supports 16-bit/24-bit, Audio encoding: AMR-NB, AMR-WB, AAC, OGG, ADPCM Audio decoding: WAV, MP3, MP2, AAC,AMR-NB, AMR-WB, IDI, Vorbis, APE,AAC-plus v1, AAC-plus v2, FLAC, WMA,ADPCM



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Connectivity	Description
WLAN	Dual-band (2.4GHz/5Ghz) 802.11 a/b/g/n 802.11 d/h/k compliant Security: WFA WPA/WPA2 personal, WPS2.0, WAPI (hardware) Max data Rates 802.11n 40Mhz/150Mbps
Bluetooth	Bluetooth v4.2 Low Energy (LE) Compatible 2.1+EDR/3.0+HS
GPS	GPS/Glonass/Beidou/Galileo dual-band reception concurrently Supports SBAS (Satellite-Based Augmentation Systems)-WAAS/MSAS/EGNOS/GAGAN
NFC	By add on another module to support
FM	65-108MHz with 50kHz step RDS/RBDS
Other Input/Output	Description
Extensional I/O	Low speed: I2C/SPI/SPI/SD/ UART/I2S/SIM/Keypad/GPIO High speed: MIPI LCD/MIPI Camera/USB Analog: MIC/Speaker/Receiver/Headset/ADC
Other Input/Output	Description
Power down	98uA
Standby Without SIM	2.8mA
Standby with SIM	4.7mA
Mp3 play on back	102 mA
H. 264 play	248mA
LTE video play	378mA



3 Platform Features

- **General**
 - Smartphone, two MCU subsystems architecture
 - eMMC on board (8GB/16GB/32GB) optional
 - LPDDR-3 (1GB/2GB/3GB) optional
- **AP MCU subsystem**
 - Octa-core ARM® 1.28GHz Cortex-A53 MPCore™
 - NEON multimedia processing engine with SIMDv2/VFPv4 ISA support
 - 32KB L1 I-cache and 32KB L1 D-cache
 - 512KB unified L2 cache for one quad-core and 256KB for another quad-core
 - DVFS technology with adaptive operating voltage from 0.85V to 1.25V
- **MD MCU subsystem**
 - ARM® Cortex-R4 processor with max. 600MHz operation frequency
 - 64KB I-cache, 64KB D-cache
 - 512KB TCM (tightly-coupled memory)
 - Coresonic DSP for running LTE modem tasks, with max. 240MHz operation frequency
 - FD216 DSP for running modem/voice tasks, with max. 250MHz operation frequency
 - High-performance AXI and AHB bus
 - General DMA engine and dedicated DMA channels for peripheral data transfer
 - Watchdog timer for system error recovery
 - Power management for clock gating control
- **MD external interfaces**
 - Dual SIM/USIM interface
 - Interface pins with RF and radio-related peripherals (antenna tuner, PA, etc.)
- **Security**
 - ARM® TrustZone® Security
- **External memory interface**
 - LPDDR2/3 up to 3GB
 - Single channel with 32-bit data bus width
 - Memory clock up to 667MHz
 - Self-refresh/partial self-refresh mode
 - Low-power operation
 - Programmable slew rate for memory controller's IO pads
 - Dual rank memory device
 - Advanced bandwidth arbitration control



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- **Peripherals**

- USB2.0 HS/FS support
- eMMC5.1
- 3 UART for debugging and applications
- SPI master for external device
- 3 I²C to control peripheral devices, e.g. CMOS image sensor, LCM or FM receiver module
- Max. 5 PWM channels (depending on system configuration/IO usage)
- I²S for connection with optional external hi-end audio codec
- GPIOs
- 1 sets of memory card controllers supporting SD/SDHC/MS/MSPRO/MMC and SDIO2.0/3.0 protocols

- **Operating conditions**

- Vbat voltage: 4V
- I/O voltage: 1.8V
- LCM interface: 1.8V

- **Package**

- Type: QFN162
- 52.7mm*41mm
- Height: Max. 3.4mm
- Ball count: 162 balls
- Ball pitch: 1.1mm



3.1 MODEM Features

- **LTE**
 - FDD: Up to 150Mbps downlink, 50Mbps uplink
 - TDD: Up to 150Mbps downlink, 50Mbps uplink
 - 1.4 to 20MHz RF bandwidth
 - 2*2 downlink SU-MIMO;
 - IPv6, QoS
 - Inter-RAT capabilities with HSPA+, EDGE and applicable backward- compatible modes
 - SNOW3G/ZUC cipher offload engine
- **3G UMTS FDD supported features**
 - 3G modem supports most main features in 3GPP Release 7 and Release 8
 - CPC (DTX in CELL_DCH, UL DRX DL DRX), HS-SCCH-less, HS-DSCH
 - Dual cell operation
 - MAC-ehs
 - 2 DRX (receiver diversity) schemes in URA_PCH and CELL_PCH
 - Uplink Cat. 7 (16QAM), throughput up to 11.5Mbps
 - Downlink Cat. 24 (64QAM, dual-cell HSDPA), throughput up to 42.2Mbps
 - Fast dormancy
 - ETWS
 - Network selection enhancements
- **Radio interface and baseband front- end**
 - High dynamic range delta-sigma ADC converts the downlink analog I and Q signals to digital baseband.
 - 10-bit D/A converter for Automatic Power Control (APC)
 - Programmable radio Rx filter with adaptive gain control
 - Dedicated Rx filter for FB acquisition
 - Baseband Parallel Interface (BPI) with programmable driving strength
 - Supports multi-band
- **GSM modem and voice CODEC**
 - Dial tone generation
 - Noise reduction
 - Echo suppression
 - Advanced side-tone oscillation reduction
 - Digital side-tone generator with programmable gain
 - 2 programmable acoustic compensation filters
 - GSM quad vocoders for adaptive multi- rate (AMR), enhanced full rate (EFR), full rate (FR) and half rate (HR)

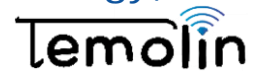


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- GSM channel coding, equalization and A5/1, A5/2 and A5/3 ciphering
- GPRS GEA1, GEA2 and GEA3 ciphering
- Programmable GSM/GPRS/EDGE modem
- Packet switched data with CS1/CS2/CS3/CS4 coding schemes
- GSM circuit switch data
- GPRS/EDGE Class 12
- Supports SAIC (Single Antenna Interference Cancellation) technology
- VAMOS (Voice services over Adaptive Multi-user channels on One Slot) technology in R9 spec



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3.2 Connectivity Features

M101C includes four wireless connectivity functions:

- WLAN
- Bluetooth
- GPS
- FM Receiver

The RF parts of those four blocks are placed on chip MT6625. With four advanced radio technologies integrated on one chip, The M101C is the best and most convenient connectivity solution in the industry. M101C implements advanced and sophisticated Radio Coexistence algorithms and hardware mechanisms. It supports single antenna sharing among 2.4 GHz Bluetooth, 2.4GHz/5GHz WLAN and 1.575 GHz for GPS. The enhanced overall quality is achieved for simultaneous voice, data and audio/video transmission on Media Devices. The small footprint with low-power consumption greatly reduces PCB layout resource.

- **Supports integrated WIFI/BlueTooth/GPS**
 - Single antenna for Bluetooth and WLAN/GPS/Bluetooth
 - Self calibration
 - Single TCXO and TMS for GPS, BT and WLAN
 - Best-in-class current consumption performance
 - Intelligent BT/WLAN coexistence scheme that goes beyond PTA signaling (e.g. transmit window and duration that take into account protocol exchange sequence, frequency, etc.)



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- **Wi-Fi**

- Dual-band (2.4GHz/5GHz) single stream 802.11 a/b/g/n MAC/BB/RF
- 802.11 d/h/k compliant
- Security: WPA WPA/WPA2 personal, WPS2.0, WAPI (hardware)
- QoS: WPA WMM, WMM PS
- 802.11n optional features: STBC, A-MPDU, Blk-Ack, RIFS, MCS Feedback, 20/40MHz coexistence (PCO), unscheduled PSMP
- Supports 802.11w protected managed frames
- Supports Wi-Fi Direct (WPA P-2-P standard) and Wi-Fi Miracast (Wi-Fi Display)
- Supports Wi-Fi HotSpot 2.0
- Integrated 2.4GHz PA with max. 19dBm CCK output power and 5GHz PA with max. 17dBm OFDM 54Mbps output power
- Typical Rx sensitivity with companion chip modem: -75dBm at 11g 54Mbps mode and -75.5dBm at 11a 54Mbps mode
- Per packet TX power control

- **BlueTooth**

- Bluetooth specification v2.1+EDR
- Bluetooth specification 3.0+HS compliance
- Bluetooth v4.0 Low Energy (LE)
- Integrated PA with 6dBm (class 1) transmit power
- Typical Rx sensitivity with companion chip modem: GFSK -92.5dBm, DQPSK -91.5dBm, 8-DPSK -86dBm
- Best-in-class BT/Wi-Fi coexistence performance
- Up to 4 piconets simultaneously with background inquiry/page scan
- Supports Scatternet
- Packet Loss Concealment (PLC) function for better voice quality
- Low-power scan function to reduce power consumption in scan modes

- **GPS**

- GPS/Glonass/Beidou/Galileo/ QZSS tri- band reception concurrently
- Supports SBAS (Satellite-Based Augmentation Systems): WAAS/MSAS/EGNOS/GAGAN
- Best-in-class sensitivity performance
 - -165 dBm tracking sensitivity
 - -163 dBm hot start sensitivity
 - -148 dBm cold start sensitivity
 - -151 dBm warm start sensitivity
- AGPS sensitivity is 6dB design margin over 3GPP
- Full A-GPS capability (E911/SUPL/EPO/HotStill)
- Active interference cancellation for up to 12 in-band tones
- Supports both TCXO and TMS (Thermistor Crystal) clock source
- 5Hz update rate



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- **FM**
 - 65-108MHz with 50kHz step
 - RDS/RBDS
 - Digital stereo demodulator
 - Simplified digital audio interface (I²S)
 - Stereo noise reduction
 - Audio sensitivity 2dBμVemf (SINAD=26dB)
 - Audio SINAD 60dB
 - Anti-jamming
 - Integrated short antenna
- **WBT IPD**
 - Integrated matching network, balance band-pass filter, GPS-WBT diplexer
 - Fully integrated in M101C module
 - Single antenna operation
- **GPS IPD**
 - Integrated high-pass type matching network and 5th-order ellipse low-pass filter
 - Fully integrated in M101C module
 - Single antenna operation



4 Interface Overview

M101C Module show as the picture:

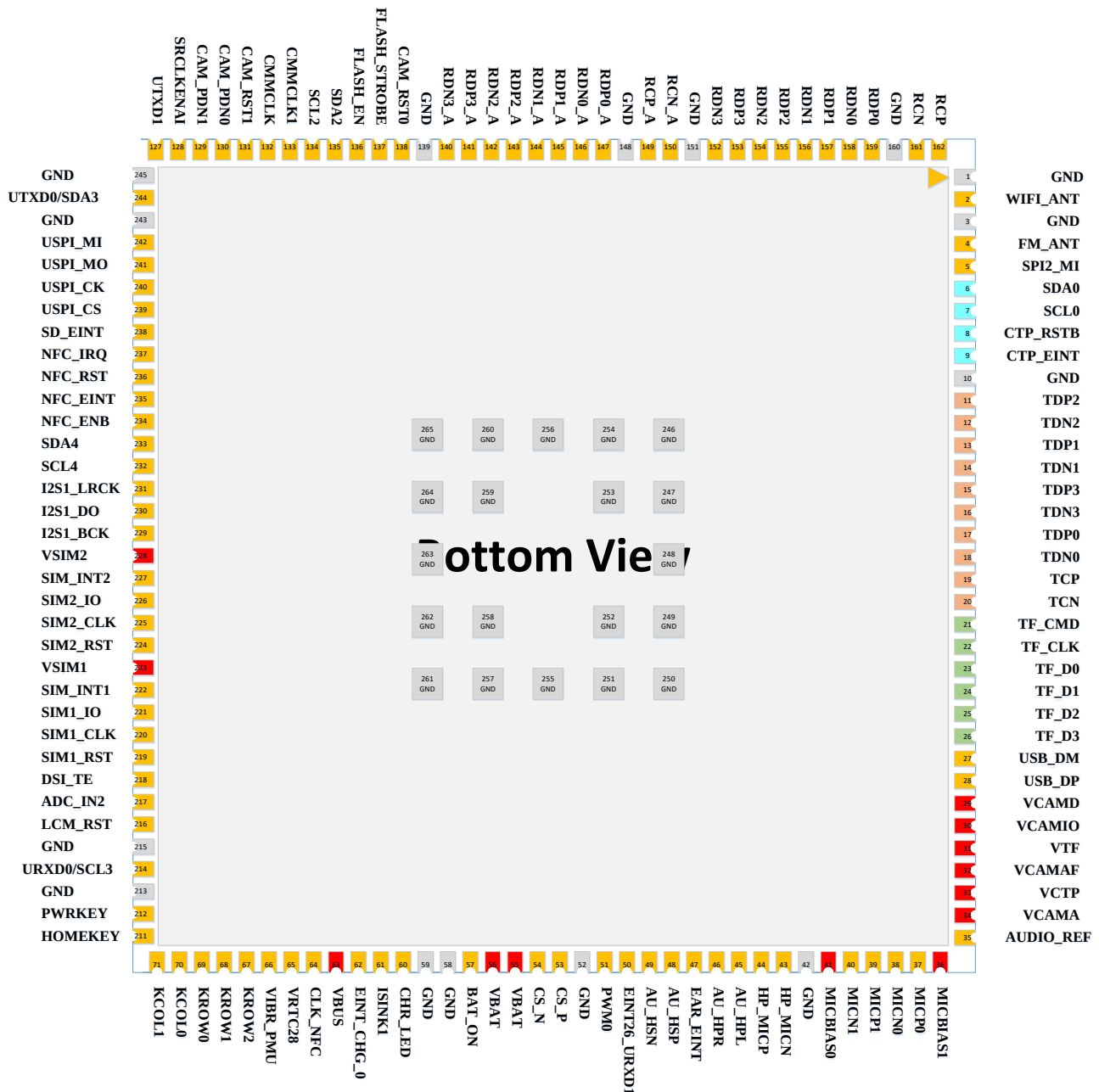


Figure: Pin Bottom view of M101C module

The following figure shows a block diagram of M101C and illustrates the major functional parts.



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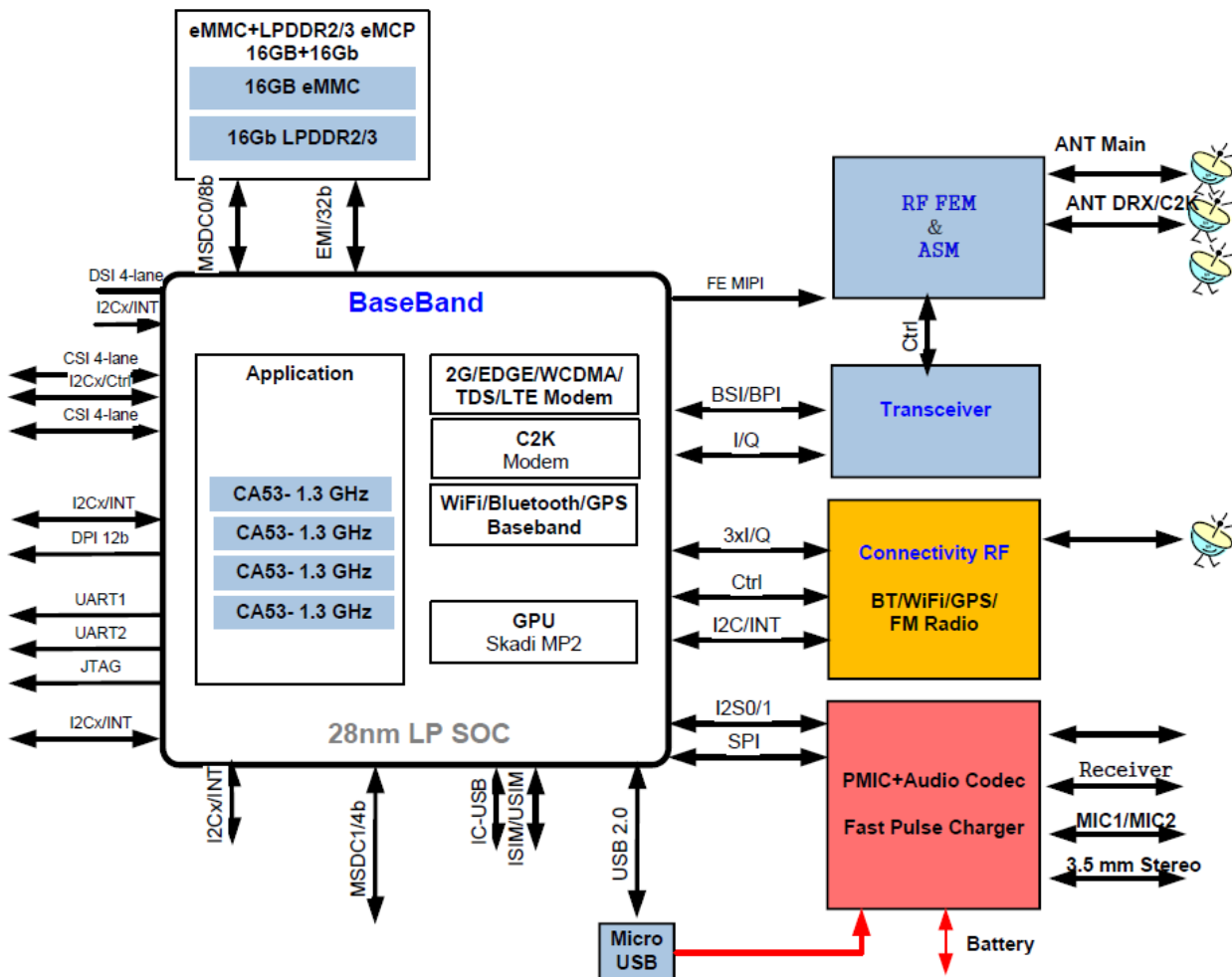


Figure: Functional Diagram

All Interface for user application detail show as following:

Table 1 : M101C hardware interface total view

◇ Storage		
1	ROM (EMMC)	16GB
2	RAM (LPDDR3)	2GB
◇ Wireless		
1	Bluetooth	BT4.0 with A2DP / BLE
2	Wi-Fi	802.11
3	GPS	Global Position System
4	NFC	Support by external NFC module
5	FM	FM onboard
◇ Interface		

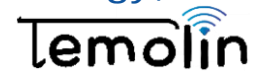


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1	USB with OTG	USB high speed 2.0
2	Storage Card	UHS SD3.0
3	I2C	x4
4	UART	x3
5	I2S	x1
6	SPI	x1
7	DPI(RGB LCD)	x1
8	DSI(MIPI LCD)	x1
9	CSI(CAMERA)	x2
10	GPIO	
11	SIM	x2
12	MIC	x2
13	Headset	x1
14	Receiver	x1
15	Speaker	x1
16	Keypad	3x2x2
17	LED	x2
18	ADC	x1
19	RTC	x1
20	ANT	x3
21	FM ANT	x1



5 Interface description

Table 1: I/O type description

◇	I/O TYPE	Description
1	IO	Digital input/output
2	DI	Digital input
3	DO	Digital output
4	PI	Power supply input
5	PO	Power supply output
6	AI	Analog input
7	AO	Analog output
8	OD	Open drain
9	VSS	Ground
10	ANT	Antenna
11	LVDS	Low Voltage Differential Signaling

Table 2: M101C pin description

Pin No.	Name	I/O Type	DC Feature	Description
1	GND	VSS		Ground
2	WIFI_ANT	ANT	50ΩRF	WIFI Antenna
3	GND	VSS		Ground
4	FM_ANT	ANT	50ΩRF	FM Antenna Positive
5	SPI2_MI	IO	1.8V Domain	GPIO
6	SDA0	OD	1.8V Domain	I2C0 data
7	SCL0	OD	1.8V Domain	I2C0 clock
8	CTP_RSTB	IO	1.8V Domain	GPIO
9	CTP_EINT	IO	1.8V Domain	GPIO
10	GND	VSS		Ground
11	TDP2	LVDS		Display MIPI Data out2+
12	TDN2	LVDS		Display MIPI Data out2-
13	TDP1	LVDS		Display MIPI Data out1+
14	TDN1	LVDS		Display MIPI Data out1-
15	TDP3	LVDS		Display MIPI Data out3+
16	TDN3	LVDS		Display MIPI Data out3-
17	TDP0	LVDS		Display MIPI Data out0+



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18	TDN0	LVDS		Display MIPI Data out0-
19	TCP	LVDS		Display MIPI clock out+
20	TCN	LVDS		Display MIPI clock out-
21	TF_CMD	IO	1.8/2.8V Auto	SD Card command
22	TF_CLK	IO	1.8/2.8V Auto	SD Card clock
23	TF_D0	IO	1.8/2.8V Auto	SD Card data0
24	TF_D1	IO	1.8/2.8V Auto	SD Card data1
25	TF_D2	IO	1.8/2.8V Auto	SD Card data2
26	TF_D3	IO	1.8/2.8V Auto	SD Card data3
27	USB_DM	LVDS	difference 90Ω	USB 2.0 D-
28	USB_DP	LVDS	difference 90Ω	USB 2.0 D+
29	VCAMD	PO	Vout = 0.9~1.5V Vdef = 1.3V Iomax = 500mA	Camera Digital Core Power
30	VCAMIO	PO	Vout = 1.2~1.8V Vdef = 1.8V Iomax = 200mA	Camera IO Power
31	VTF	PO	Vout = 2.9~3.3V Vdef = 2.9V Iomax = 800mA	SD Card Power
32	VCAMAF	PO	Vout = 1.2~3.3V Vdef = 2.8V Iomax = 200mA	Camera AF Motor Power
33	VTP	PO	Vout = 1.2~3.3V Vdef = 2.8V Iomax = 200mA	Touch Pannel IC Power
34	VCAMA	PO	Vout = 1.5~2.8V Vdef = 2.8V Iomax = 200mA	Camera Analog Power
35	AUDIO_REF	VSS	Connect to GND	Audio Referen Gnd
36	MICBIAS1	PO	Vout = 1.7~2.5V Vdef = 2.5V Iomax = 3mA	Headset MIC Power
37	MICP0	AI		MIC input 1+
38	MICN0	AI		MIC input 1-
39	MICP1	AI		MIC input 2+
40	MICN1	AI		MIC input 2-
41	MICBIAS0	PO		MIC Power
42	GND	VSS		Ground



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43	HP_MICN	AI		Headset MIC input-
44	HP_MICP	AI		Headset MIC input+
45	AU_HPL	AO		Headset Line Out Left
46	AU_HPR	AO		Headset Line Out Right
47	EAR_EINT	IO	Default Hi	Headset Interrupt
48	AU_HSP	AO		Audio Receiver+
49	AU_HSN	AO		Audio Receiver-
50	EINT26_URXD1	IO	1.8V Domain	GPIO
51	PWM0	AO	1.8V Domain	GPIO
52	GND	VSS		Ground
53	CS_P	AI		Power meter input +
54	CS_N	AI		Power meter input -
55	VBAT	PI	Vmax = 4.4V Vmin = 3.5V	Battery Power input 3.5~4.2V
56	VBAT	PI	Vnorm = 4V	Battery Power input 3.5~4.2V
57	BAT_ON	AO	25°C Vdef = 0.68V	Battery temperature detect
58	GND	VSS		Ground
59	GND	VSS		Ground
60	CHR_LED	OD	0~24mA	Charge LED
61	ISINK1	OD	0~24mA	Status LED
62	EINT_CHG_0	IO	1.8V Domain	GPIO
63	VBUS	PI		USB VBUS
64	CLK_NFC	AO		26MHz Clock Output
65	VRTC	PIO	Vout = 2.2~3.0V Vdef = 2.8V Iomax = 2mA Iimax = 100uA	Backup Battery input
66	VIBR	PO	Vout = 1.2~3.3V Vdef = 2.8V Iomax = 100mA	Vibration motor Power
67	KROW2	IO	1.8V Domain	Key Row2
68	KROW1	IO	1.8V Domain	Key Row1
69	KROW0	IO	1.8V Domain	Key Row0
70	KCOL0	IO	1.8V Domain No used as output	Key Col0
71	KCOL1	IO	1.8V Domain	Key Col1



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			No used as output	
82/211	HOMEKEY	DI	1.8V Domain	Home Key
83/212	PWRKEY	DI	Internal weak pull-up to VBAT	Power Key
84/213	GND	VSS		Ground
85/214	SCL3	IO	1.8V Domain	I2C3 CLK
86/215	GND	VSS		
87/216	LCM_RST	IO	1.8V Domain	GPIO
88/217	ADC_IN2	AI	0~1.45V 12bit sample rate 1KHz	Analog ADC Input
89/218	DSI_TE	IO	1.8V Domain	GPIO
90/219	SIM1_RST	IO	1.8/2.8V Auto	SIM1 Card Reset
91/220	SIM1_CLK	IO	1.8/2.8V Auto	SIM1 Card Clock
92/221	SIM1_IO	IO	1.8/2.8V Auto	SIM1 Card IO
93/222	SIM_INT1	IO	1.8/2.8V Auto	SIM1 Card Detect
94/223	VSIM1	PO	Vout = 1.8~3.1V Vdef = 1.8V Iomax = 50mA	SIM1 Power
95/224	SIM2_RST	IO	1.8/2.8V Auto	SIM2 RST
96/225	SIM2_CLK	IO	1.8/2.8V Auto	SIM2 CLK
97/226	SIM2_IO	IO	1.8/2.8V Auto	SIM2 IO
98/227	SIM_INT2	IO	1.8/2.8V Auto	SIM2 Card Detect
99/228	VSIM2	PO	Vout = 1.8~3.1V Vdef = 1.8V Iomax = 50mA	SIM2 Power
100/229	I2S1_BCK	IO	1.8V Domain	GPIO
101/230	I2S1_DO	IO	1.8V Domain	GPIO
102/231	I2S1_LRCK	IO	1.8V Domain	GPIO
103/232	SCL4	OD	1.8V Domain	I2C4 CLK
104/233	SDA4	OD	1.8V Domain	I2C4 SDA
105/234	NFC_ENB	IO	1.8V Domain	GPIO
106/235	NFC_EINT	IO	1.8V Domain	GPIO
107/236	NFC_RST	IO	1.8V Domain	GPIO
108/237	NFC_IRQ	IO	1.8V Domain	GPIO
109/238	SD_EINT	IO	1.8V Domain	GPIO
110/239	USPI_CS	IO	1.8V Domain	GPIO



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111/240	USPI_CK	IO	1.8V Domain	GPIO
112/241	USPI_MO	IO	1.8V Domain	GPIO
113/242	USPI_MI	IO	1.8V Domain	GPIO
114/243	GND	VSS		Ground
115/244	SDA3	IO	1.8V Domain	I2C3 SDA
116/245	GND	VSS		Ground
127	UTXD1	IO	1.8V Domain	GPIO
128	SRCLKENAI	IO	1.8V Domain	Clock Request
129	CAM_PDN1	IO	1.8V Domain	Camera PowerDown Ctrl1
130	CAM_PDN0	IO	1.8V Domain	Camera PowerDown Ctrl0
131	CAM_RST1	IO	1.8V Domain	GPIO
132	CMMCLK	IO	1.8V Domain	Camera1 Clock
133	CMMCLK1	IO	1.8V Domain	Camera2 Clock
134	SCL2	OD	1.8V Domain	I2C2 CLK
135	SDA2	OD	1.8V Domain	I2C2 SDA
136	FLASH_EN	IO	1.8V Domain	GPIO
137	FLASH_STROBE	IO	1.8V Domain	GPIO
138	CAM_RST0	IO	1.8V Domain	GPIO
139	GND	VSS		Ground
140	RDN3_A	LVDS		Camera2 MIPI Data3-
141	RDP3_A	LVDS		Camera2 MIPI Data3+
142	RDN2_A	LVDS		Camera2 MIPI Data2-
143	RDP2_A	LVDS		Camera2 MIPI Data2+
144	RDN1_A	LVDS		Camera2 MIPI Data1-
145	RDP1_A	LVDS		Camera2 MIPI Data1+
146	RDN0_A	LVDS		Camera2 MIPI Data0-
147	RDP0_A	LVDS		Camera2 MIPI Data0+
148	GND	VSS		Ground
149	RCP_A	LVDS		Camera2 MIPI clock+
150	RCN_A	LVDS		Camera2 MIPI clock-
151	GND	VSS		Ground
152	RDN3	LVDS		Camera1 MIPI Data3-
153	RDP3	LVDS		Camera1 MIPI Data3+
154	RDN2	LVDS		Camera1 MIPI Data2-
155	RDP2	LVDS		Camera1 MIPI Data2+
156	RDN1	LVDS		Camera1 MIPI Data1-
157	RDP1	LVDS		Camera1 MIPI Data1+
158	RDN0	LVDS		Camera1 MIPI Data0-



159	RDP0	LVDS		Camera1 MIPI Data0+
160	GND	VSS		Ground
161	RCN	LVDS		Camera1 MIPI Clock-
162	RCP	LVDS		Camera1 MIPI Clock+
246~ 265	GND	VSS		Ground

5.1 Power Supply

M101C provides four VBAT pins dedicated to connection with the external power supply. VBAT pins (pin 55/56) are used for M101C power supply part. The power supply range of this module is 3.5V~4.3V, the suggestion value is 4 V.

5.2 Decrease Power Voltage Drop

The power design for the module is very important. Make sure the input voltage will never drop below 3.1V, even if the peak current reaches 2.5A. If the voltage drops below 3.1V, the module will be turned off automatically

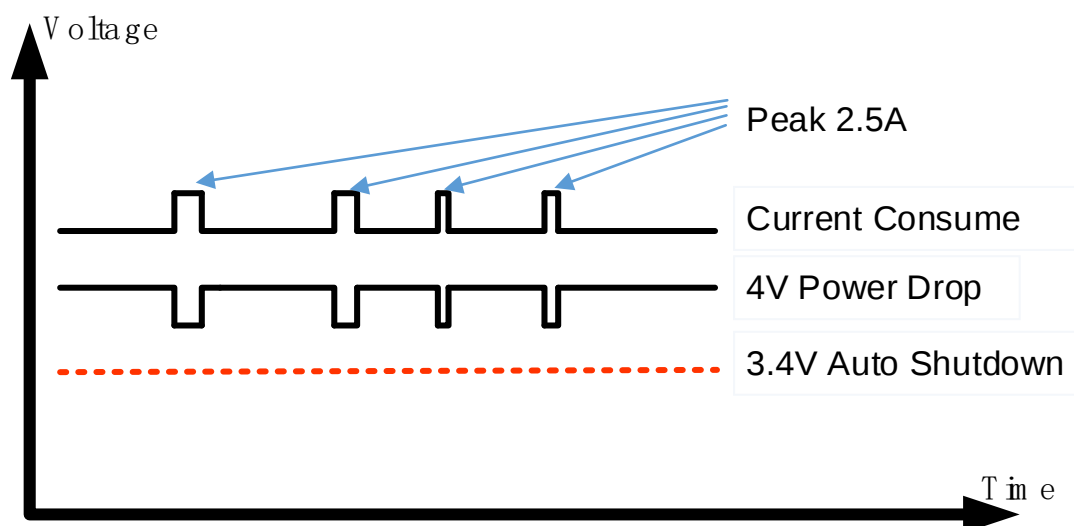


Figure: Voltage Drop on Peak Current diagram

To decrease voltage drop, a bypass capacitor of about 100 μ F with low ESR should be add. Multi-layer ceramic chip (MLCC) capacitor is recommend to be used due to its ultra-low ESR. Two ceramic capacitors (100nF, 33pF) are recommend to be applied to the VBAT pins. The main power supply from an external application has to be a single voltage source and can be expanded to two sub



paths with star structure. The width of VBAT BB trace should be no less than 1mm, and the width of VBAT RF trace should be no less than 2mm. In principle, the longer of the VBAT trace will be traced as wide as possible. In addition, in order to get a stable power source, Temolin is suggested to use a 0.5W zener diode and place it close to the VBAT pins. The following figure shows the star structure of the power supply.

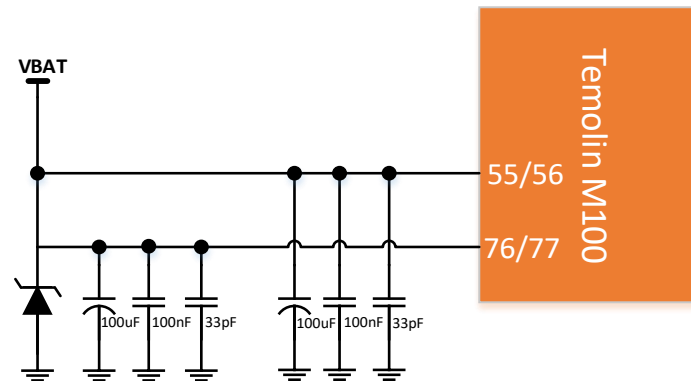


Figure : Star Structure of the Power Supply

5.3 Reference Design for Power Supply

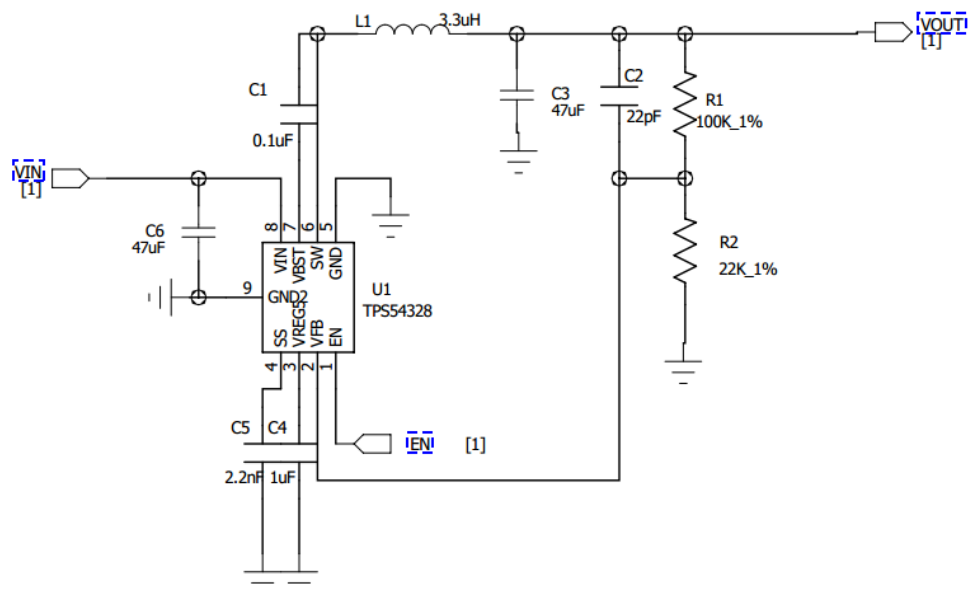


Figure: Power Supply Reference Circuit

5.4 M101C Mini System

The M101C extend mini system must be used minimum 13 pin as following pins.



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Wireless with Android

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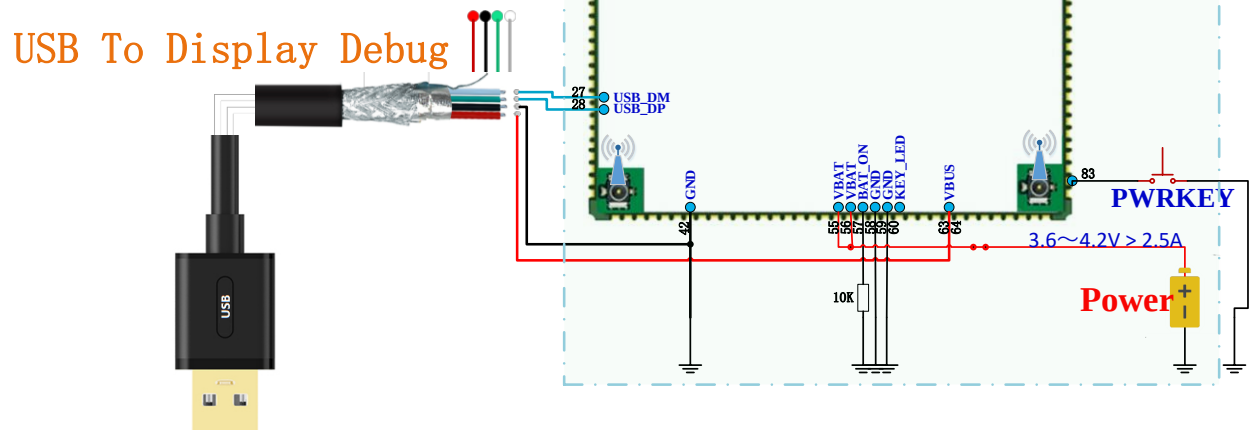
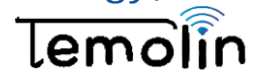


Figure :Mini System Application

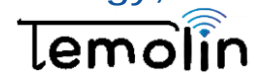


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6 Mechanical Dimensions

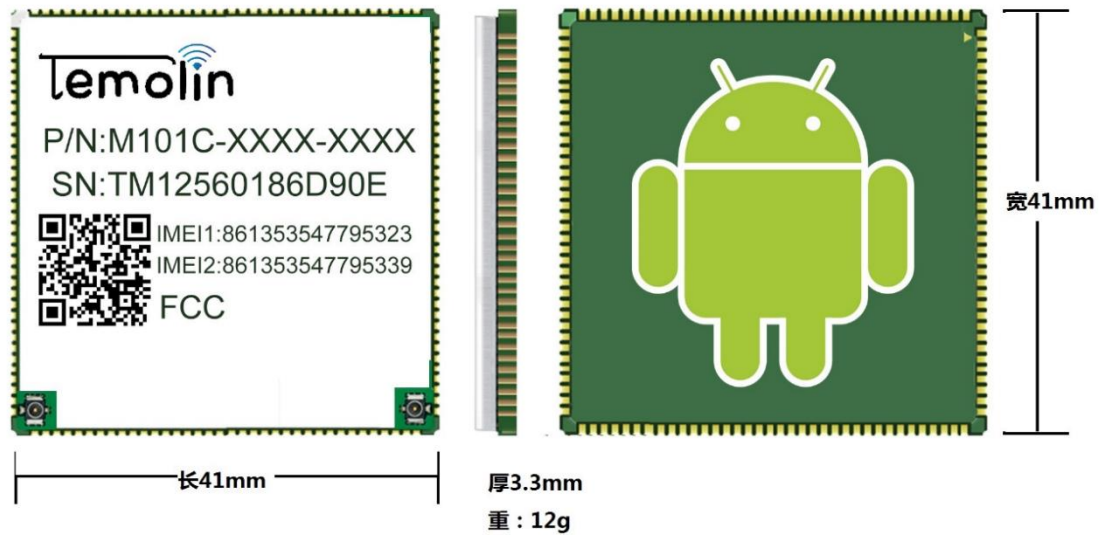


Figure :Module Top and Side Dimensions



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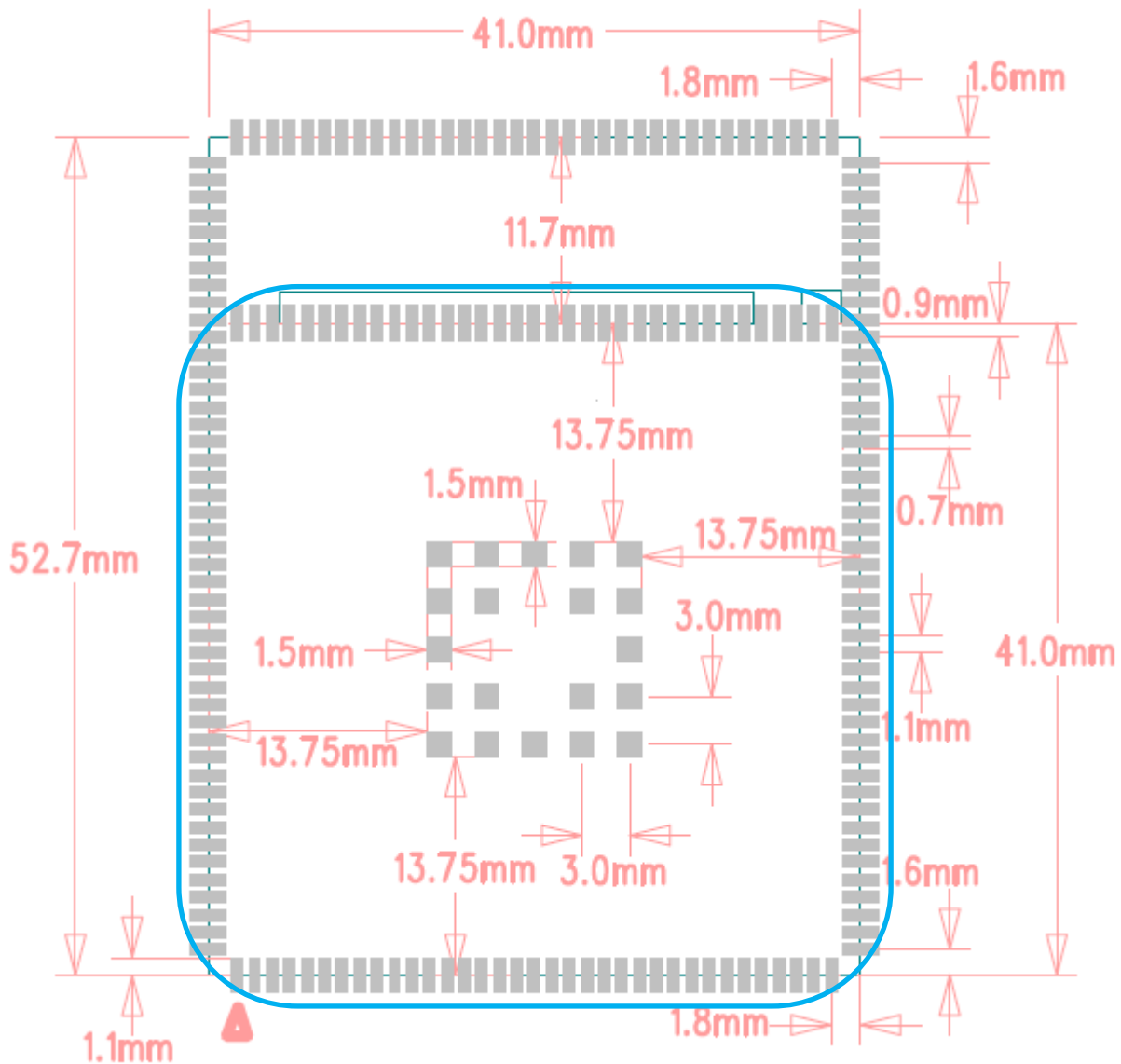
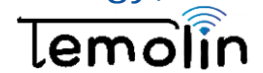


Figure : Layout PCB footprint example

Note:

M101C please refer to the Blue framework 41x41mm footprint

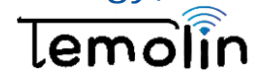


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7 Packaging

M101C is packaged in the tray packing . One tray is 26cm length and 23cm width contains 20pcs modules.

The figure below shows the package details, measured in mm:

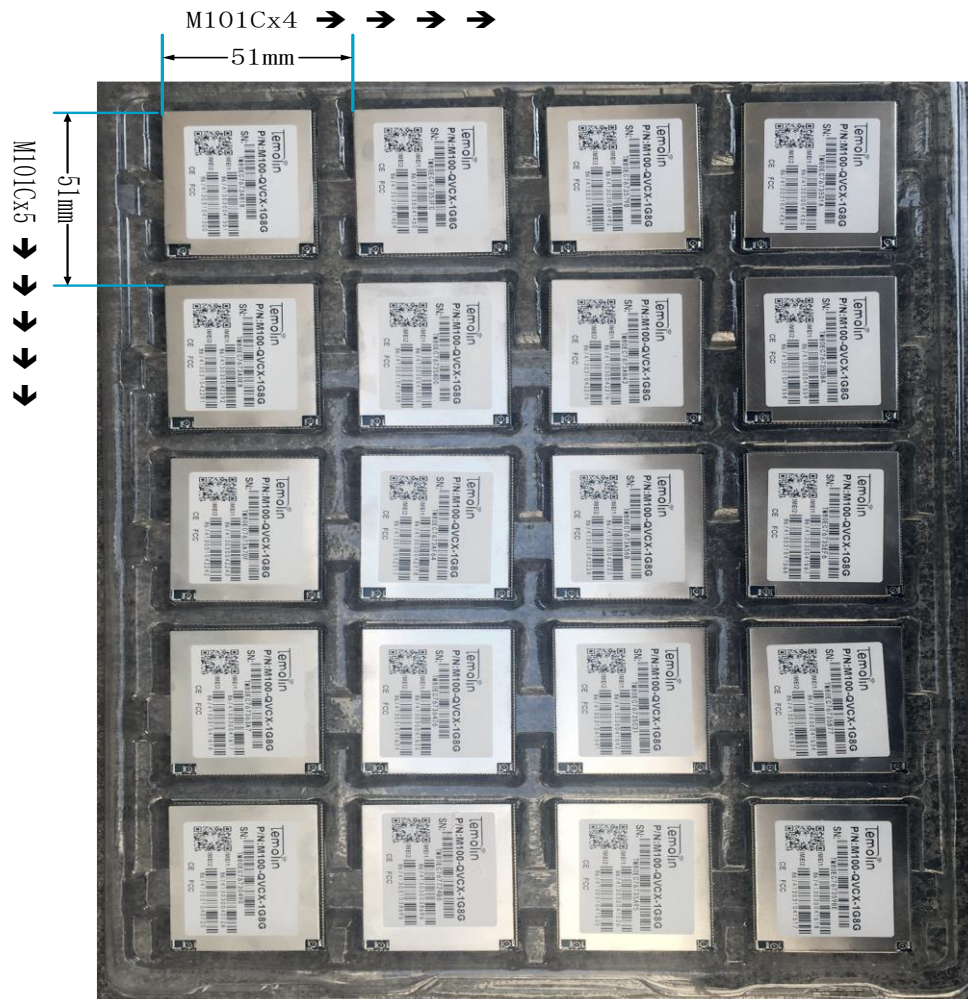


Figure: Deliver packaging example



8 Ordering information

Temolin Amlink module are available in different configurations and densities.

For part number description as following:

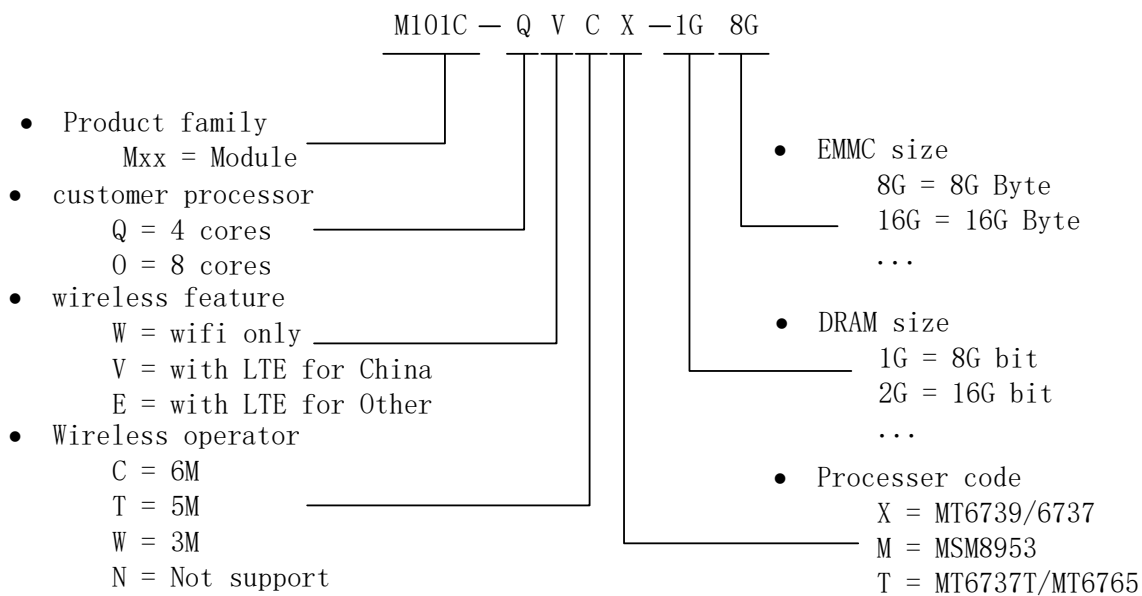


Figure: Part number description



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For ordering list of module as following:

订货代码	主频	DDR3	eMMC	WIFI/BT	定位	通信制式	最大分辨率
M101C-QVCX-1G8G	A53 4x1.28G	1G	8G	2.4/5G	北斗+GPS	全网通	1280x800
M101C-QVCX-2G16G	A53 4x1.28G	2G	16G	2.4/5G	北斗+GPS	全网通	1280x800
M101C-QVCT-1G8G	A53 4x1.28G	1G	8G	2.4/5G	北斗+GPS	全网通	1920x1080
M101C-QVCT-2G16G	A53 4x1.28G	2G	16G	2.4/5G	北斗+GPS	全网通	1920x1080
M101C-QECX-1G8G	A53 4x1.28G	1G	8G	2.4/5G	GPS+GLO	全球通	1280x800
M101C-QECX-2G16G	A53 4x1.28G	2G	16G	2.4/5G	GPS+GLO	全球通	1280x800
M101C-QECT-1G8G	A53 4x1.28G	1G	8G	2.4/5G	GPS+GLO	全球通	1920x1080
M101C-QECT-2G16G	A53 4x1.28G	2G	16G	2.4/5G	GPS+GLO	全球通	1920x1080
M101C-QVWX-1G8G	A53 4x1.28G	1G	8G	2.4/5G	北斗+GPS	移动/联通	1280x800
M101C-QVWX-2G16G	A53 4x1.28G	2G	16G	2.4/5G	北斗+GPS	移动/联通	1280x800
M101C-QVTX-1G8G	A53 4x1.28G	1G	8G	2.4/5G	北斗+GPS	移动	1280x800
M101C-QVTX-2G16G	A53 4x1.28G	2G	16G	2.4/5G	北斗+GPS	移动	1280x800
M101C-QWNX-1G8G	A53 4x1.28G	1G	8G	2.4/5G	北斗+GPS	-	1280x800
M101C-QWNX-2G16G	A53 4x1.28G	2G	16G	2.4/5G	北斗+GPS	-	1280x800

Integration instructions for host product manufacturers according to KDB 996369 D03 OEM Manual v01

2.2 List of applicable FCC rules

FCC Part 15.247&47 CFR FCC Part 15 Subpart E 15.407 &FCC CFR Title 47 Part 2, Part 22H
&FCC CFR Title 47 Part 2, Part 24E&FCC CFR Title 47 Part 2, Part 27

2.3 Specific operational use conditions

This module is stand-alone modular. If the end product will involve the Multiple simultaneously transmitting condition or different operational conditions for a stand-alone modular transmitter in a host, host manufacturer have to consult with module manufacturer for the installation method in end system.

2.4 Limited module procedures

Not applicable. The module is a Single module and complies with the requirement of FCC Part 15.212.

2.5 Trace antenna designs

Not applicable. The module has its own antenna, and doesn't need a host's printed board microstriptrace antenna etc.

2.6 RF exposure considerations

The module must be installed in the host equipment such that at least 20cm is maintained between the antenna and users' body; and if RF exposure statement or module layout is changed, then the host product manufacturer required to take responsibility of the module through a change in FCC ID or new application. The FCC ID of the module cannot be used on the final product. In these circumstances, the host manufacturer will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

2.7 Antennas

This radio transmitter **2AM5I-M101C** has been approved by Federal Communications Commission to operate with the antenna types listed below, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

Model name	Antenna type	Antenna gain
M101C	PIFA Antenna	3.0 dBi

2.8 Label and compliance information

The final end product must be labeled in a visible area with the following" Contains FCC ID:2AM5I-M101C".

2.9 Information on test modes and additional testing requirements

Host manufacturer must perform test of radiated & conducted emission and spurious emission, etc according to the actual test modes for a stand-alone modular transmitter in a host, as well as for multiple simultaneously transmitting modules or other transmitters in a host product. Only when all the test results of test modes comply with FCC requirements, then the end product can be sold legally.

2.10 Additional testing, Part 15 Subpart B disclaimer

The modular transmitter is only FCC authorized for FCC Part 15.247&47 CFR FCC Part 15 Subpart E 15.407 &FCC CFR Title 47 Part 2, Part 22H&FCC CFR Title 47 Part 2, Part 24E&FCC CFR Title 47 Part 2, Part 27 and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. If the grantee markets their product as being Part 15 Subpart B compliant (when it also contains unintentional-radiator digital circuitry), then the grantee shall provide a notice stating that the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed.

Federal Communications Commission (FCC) Statement

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Warning: Changes or modifications made to this device not expressly approved by **Temolin Technology, Inc** may void the FCC authorization to operate this device.

Note: The manufacturer is not responsible for any radio or TV interference caused by unauthorized modifications to this equipment. Such modifications could void the user's authority to operate the equipment.

RF exposure statement:

The transmitter must not be colocated or operated in conjunction with any other antenna or transmitter. This equipment complies with the FCC RF radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with a Minimum distance of 20cm between the radiator and any part of your body.